

ABSTRACT

An aspect of the present disclosure relates to a method for forming a permanent resist, the method including a step of coating a photosensitive resin composition, which contains a base polymer and a compound having an absorption peak at 360 to 500 nm and emitting light by light irradiation, to a part or the entire surface of a substrate and drying the photosensitive resin composition to form a resin film, a step of exposing at least a part of the resin film, a step of developing the exposed resin film to form a patterned resin film, and a step of heating the patterned resin film.